

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUICHI OGAWA	02/04/2015
HARUYOSHI YAMAKAWA	02/04/2015
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14423270
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DATE SIGNED:	02/23/2015
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, WE/I, Yuichi OGAWA and Haruyoshi YAMAKAWA, citizens of Japan, having addresses at c/o Kurita Water Industries Ltd., 10-1, Nakano 4-chome, Nakano-ku, Tokyo 1640001 Japan ("Assignor"), are the owners of the invention entitled "METHOD AND SYSTEM FOR CLEANING SEMICONDUCTOR SUBSTRATE ("Application"), the application having been executed on even date herewith, and/or being identifiable in the United States Patent and Trademark Office by Application No. 14/423,270, filed February 23, 2015; and

WHEREAS it is the intention of ASSIGNOR that KURITA WATER INDUSTRIES LTD., having an address at 10-1, Nakano 4-chome, Nakano-ku, Tokyo 1640001 Japan (hereinafter "ASSIGNEE"), that ASSIGNEE own all of ASSIGNOR right, title and interest in and to the Invention, including all of ASSIGNOR's U.S., foreign and international patent rights therein;

NOW THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, I transfer to Assignee, its successors and assigns, my entire right, title and interest in and to the invention, the above-identified application, corresponding domestic and foreign applications claiming rights or benefits to the above-identified application including provisional applications, non-provisional applications, continuation applications, continuing applications, divisional applications, reissue applications, reexamination applications, design applications and continuation-in-part applications, all Letters Patent(s) or similar legal protection issuing thereon, and all rights and benefits under any applicable treaty or convention, including all rights of priority; and I authorize the Commissioner of the United States Patent and Trademark Office or foreign equivalent thereof to issue the Letters Patent or similar legal protection to the ASSIGNEE.

I authorize the ASSIGNEE, its successors and assigns, to insert in this instrument the filing date and serial number of the application when ascertained.

I authorize the ASSIGNEE, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in any and all foreign countries.

I represent to the ASSIGNEE, its successors and assigns, that I have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. I, my executors or administrators, will at any time upon request, without additional consideration, but at the expense of the ASSIGNEE, its successors and assigns, execute such additional writings and do such additional acts as the ASSIGNEE, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries.

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IN TESTIMONY WHEREOF, WE/I hereby execute this Assignment on this date:

Date: 4 Feb. 2015

Yuichi Ogawa
YUICHI OGAWA

Date: 4 Feb. 2015

HARUYOSHI YAMAKAWA
HARUYOSHI YAMAKAWA